

FIG. 1a

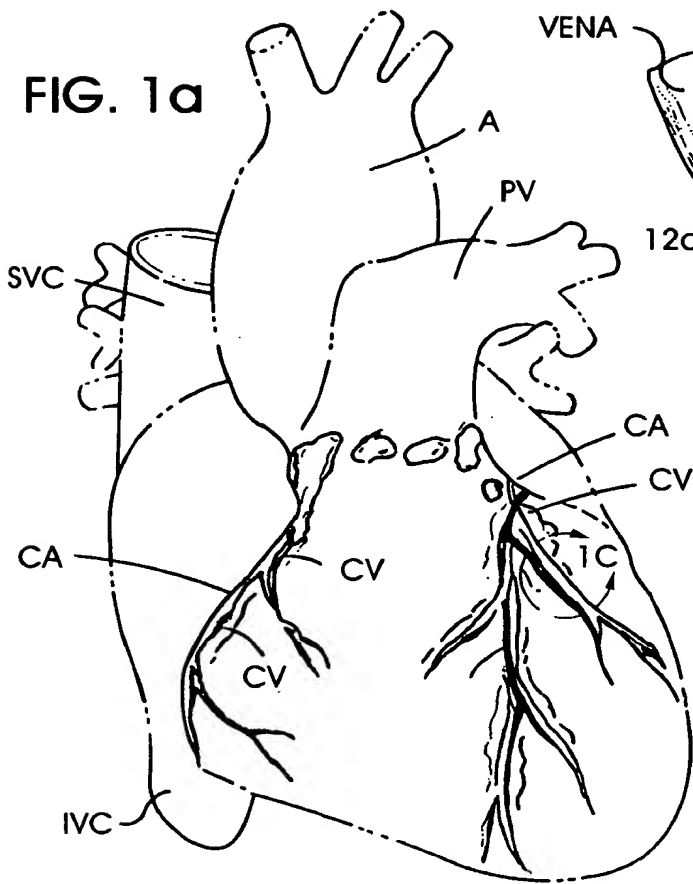


FIG. 1c

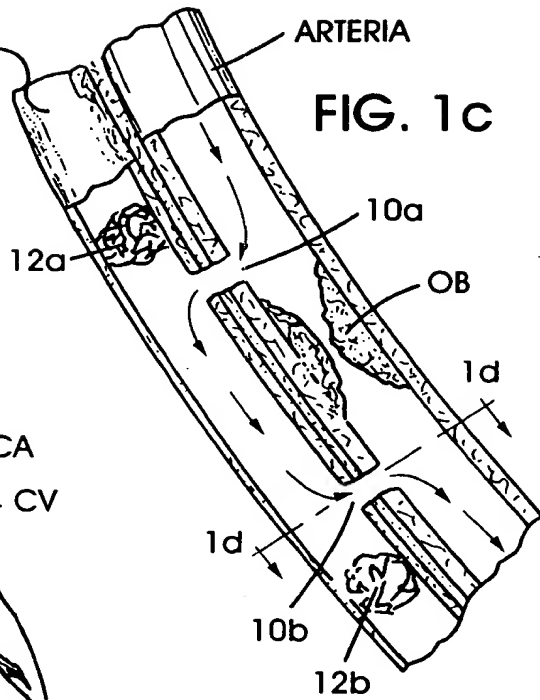


FIG. 1d

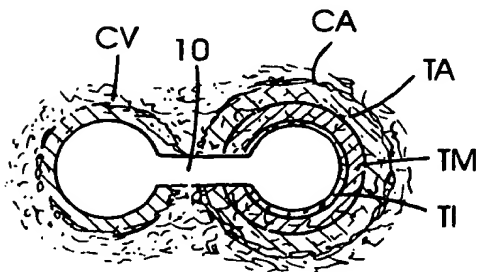
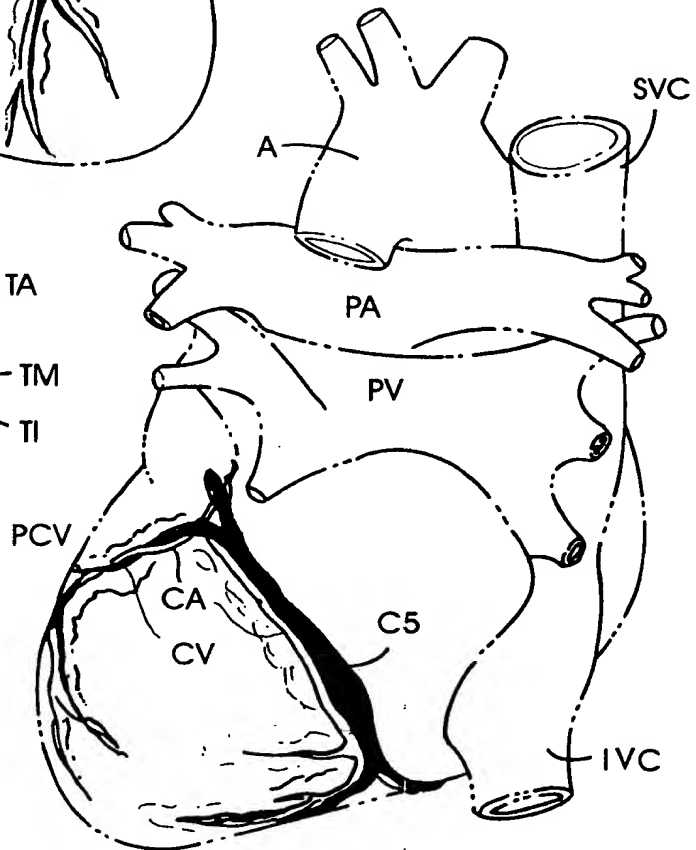


FIG. 1b



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FIG. 1e

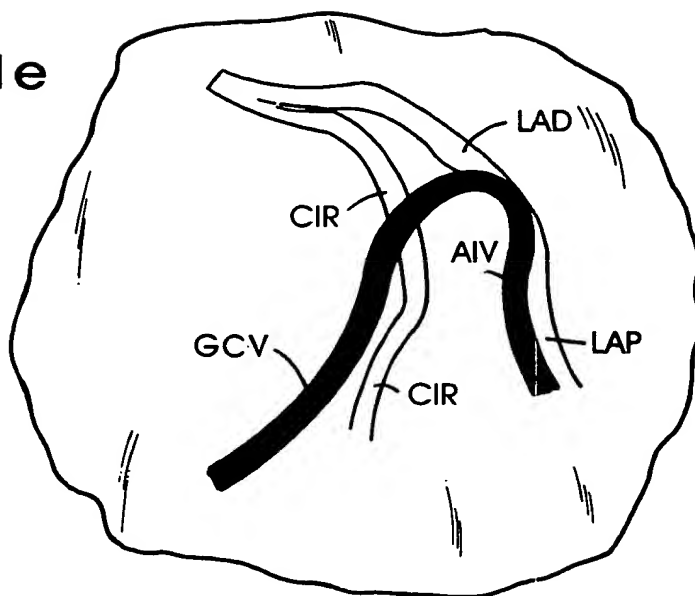


FIG. 1f

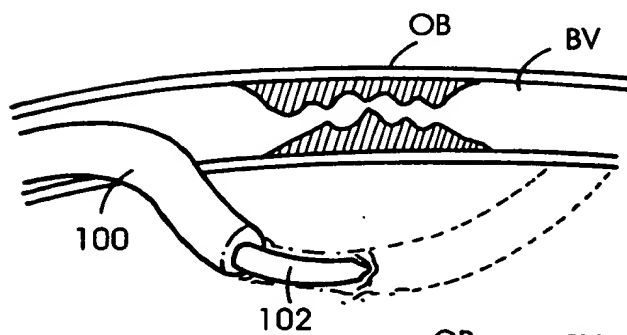
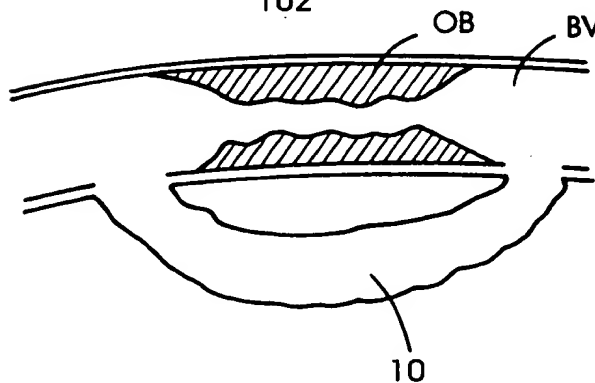


FIG. 1f'



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FIG. 2

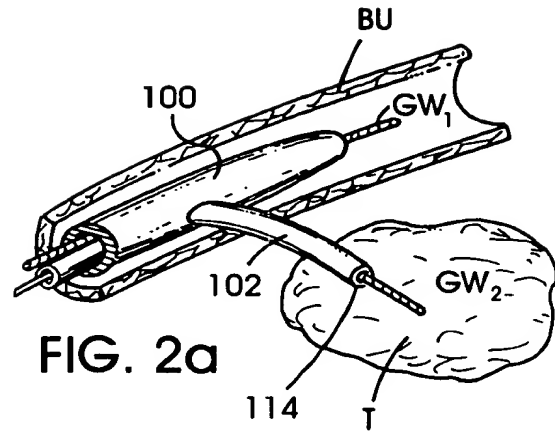
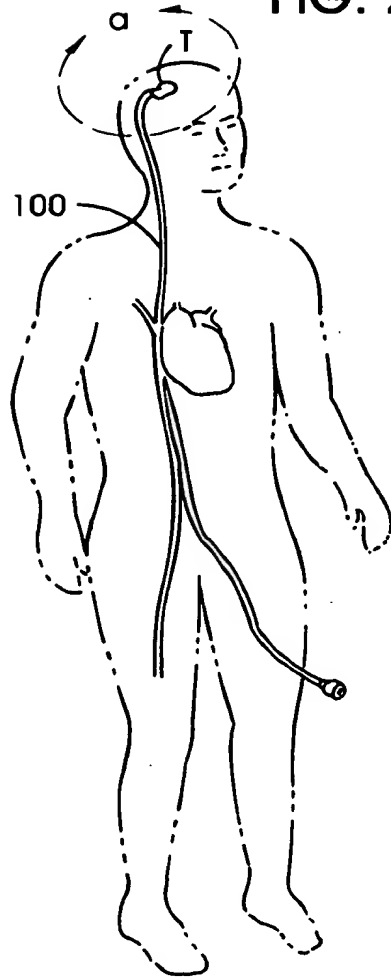


FIG. 2a

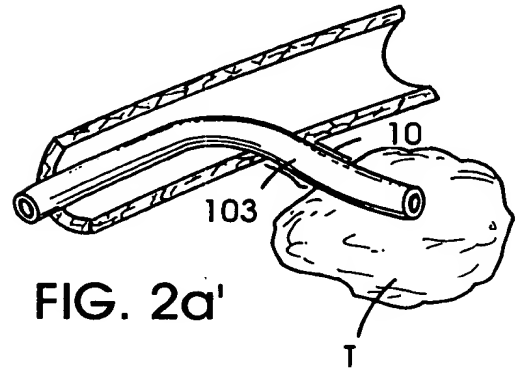


FIG. 2a'

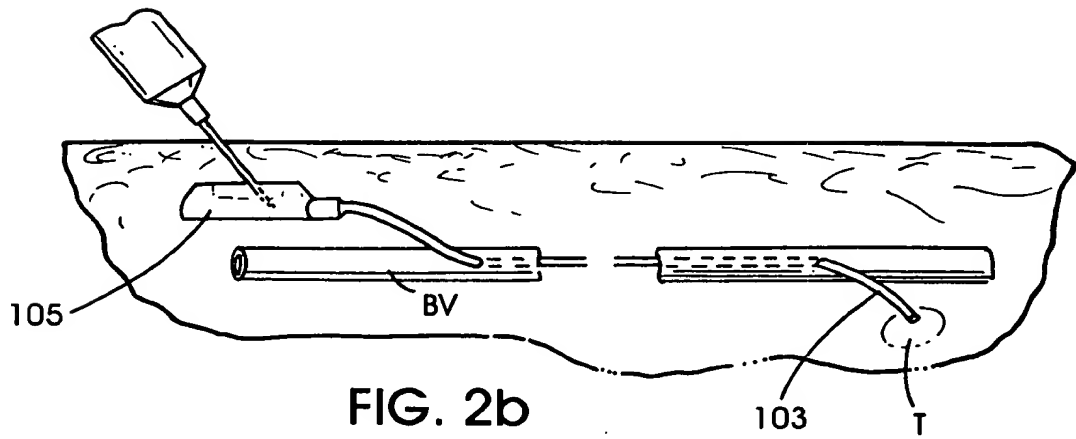


FIG. 2b

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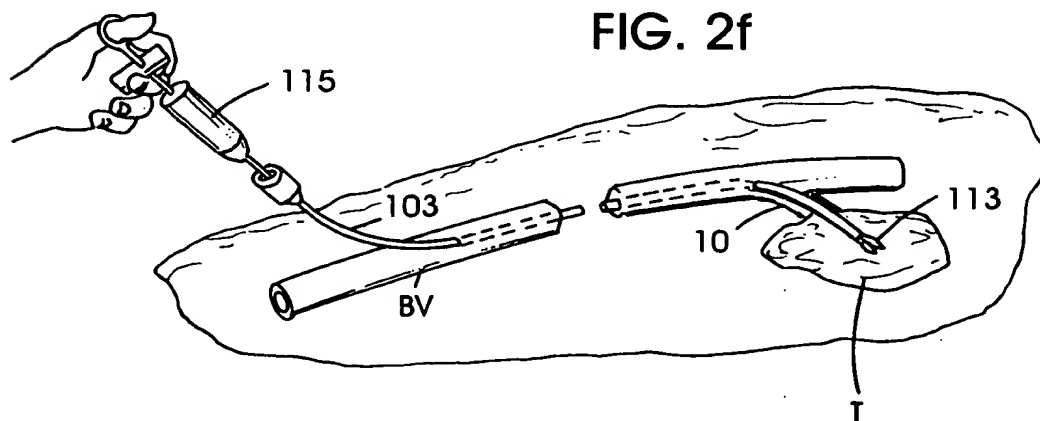
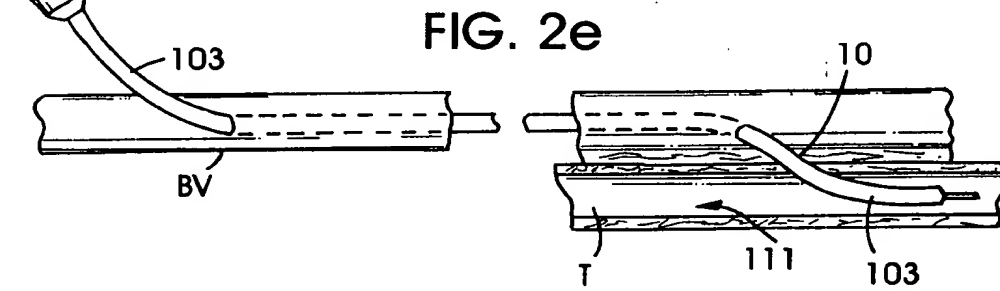
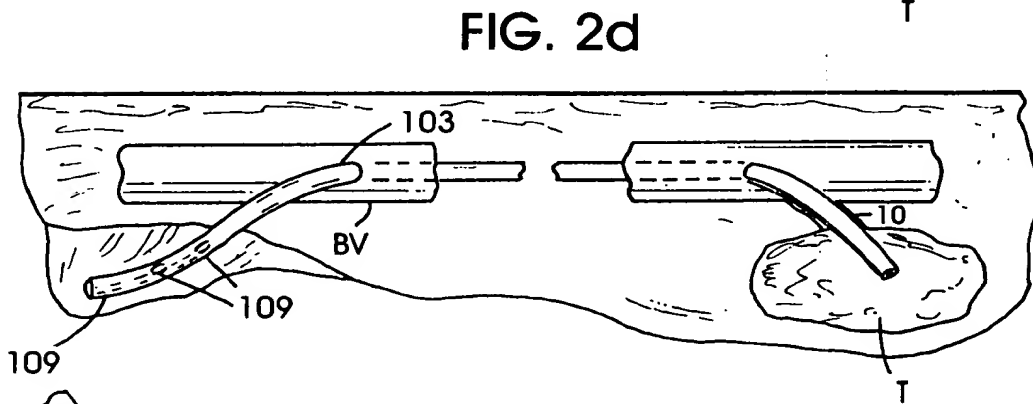
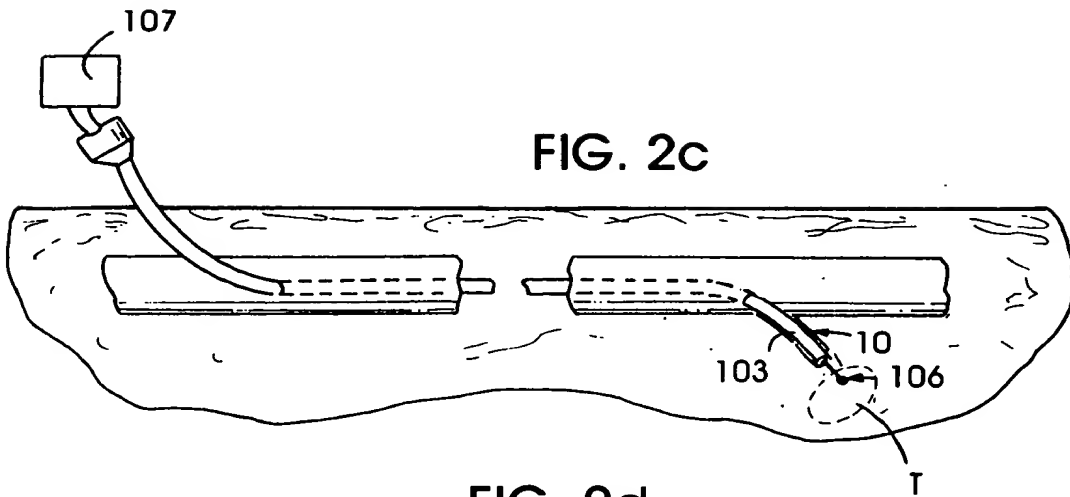


FIG. 3a

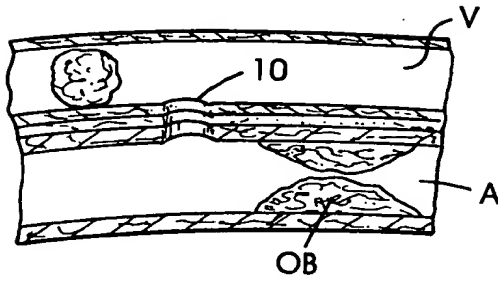


FIG. 3d

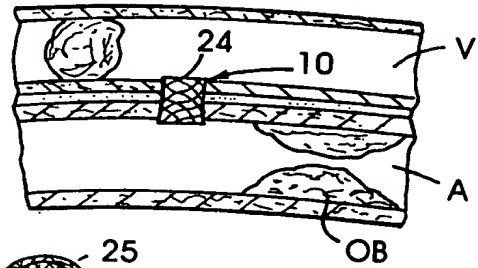


FIG. 3b

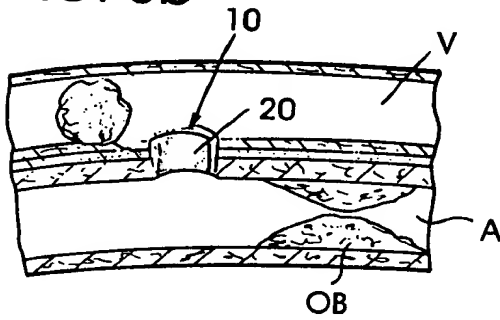


FIG. 3d'

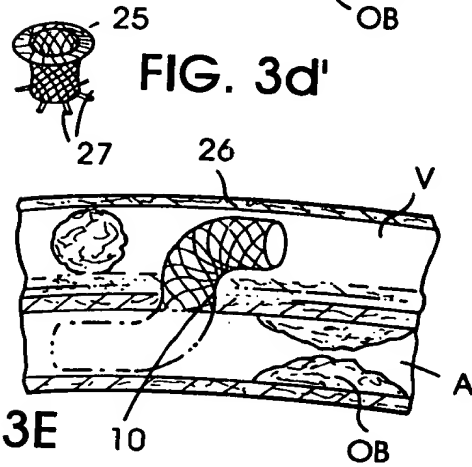


FIG. 3E

FIG. 3c

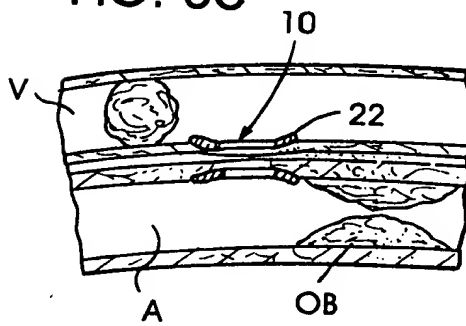
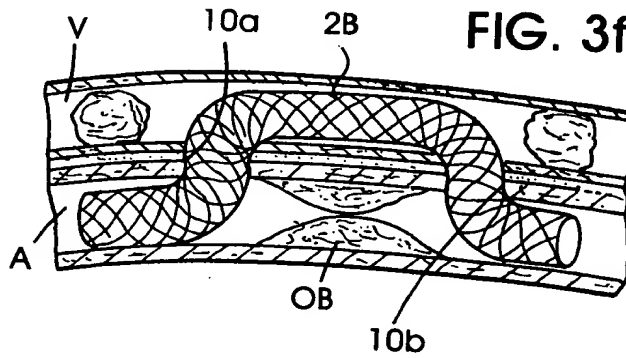


FIG. 3f



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FIG. 4a

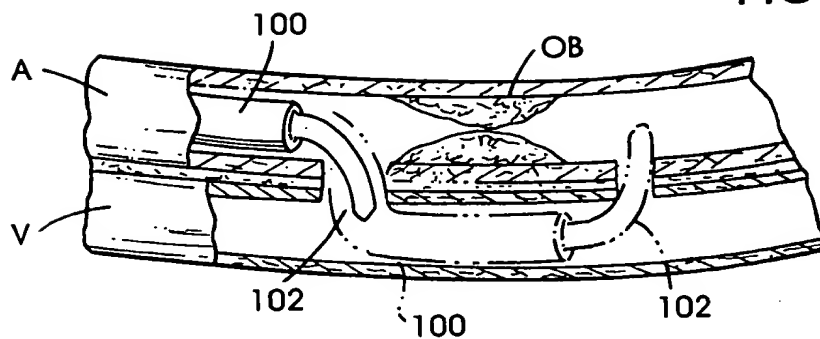


FIG. 4b

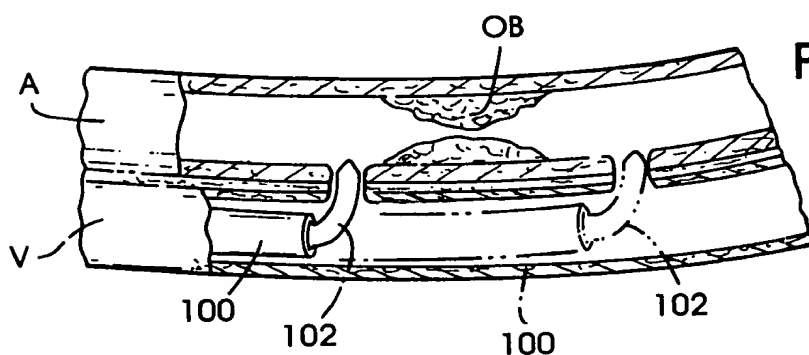


FIG. 4c

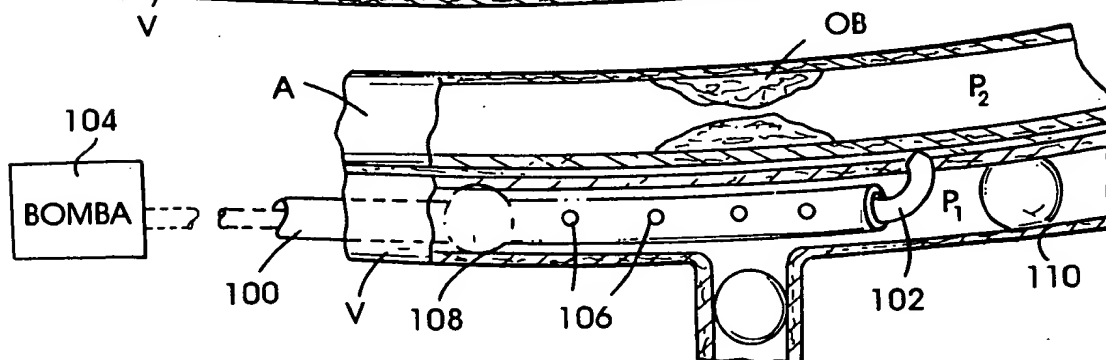
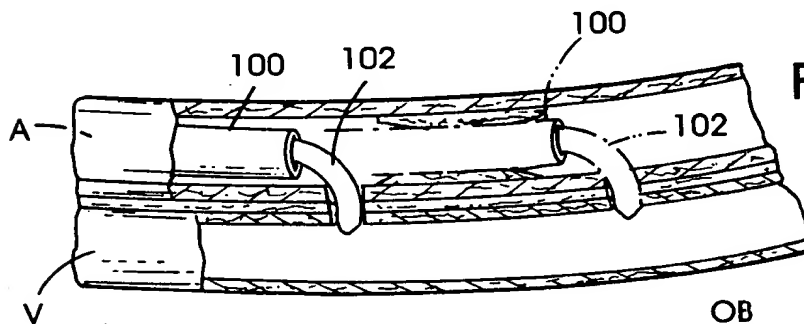
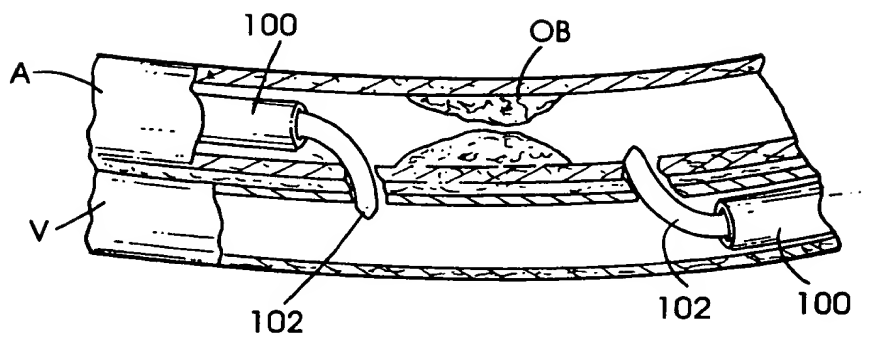


FIG. 4d

FIG. 4e



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FIG. 5a

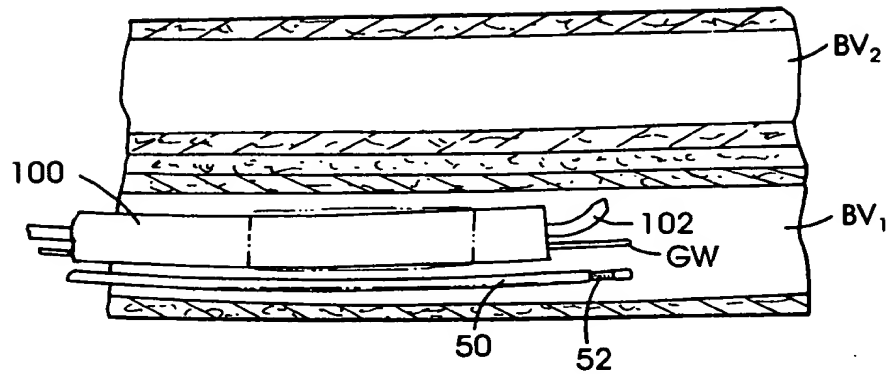


FIG. 5b

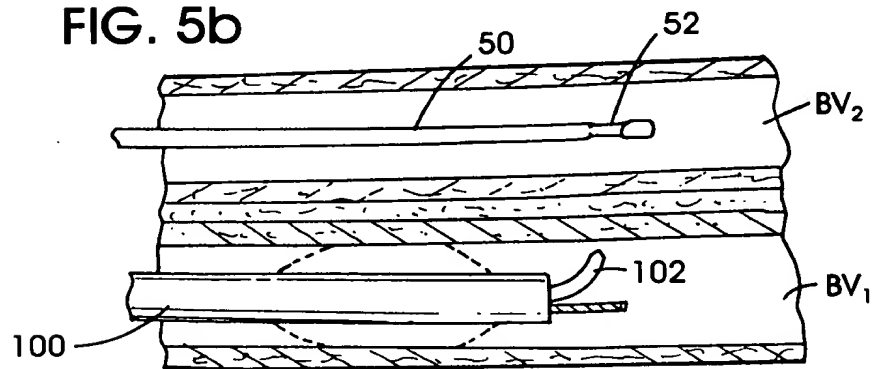


FIG. 5c

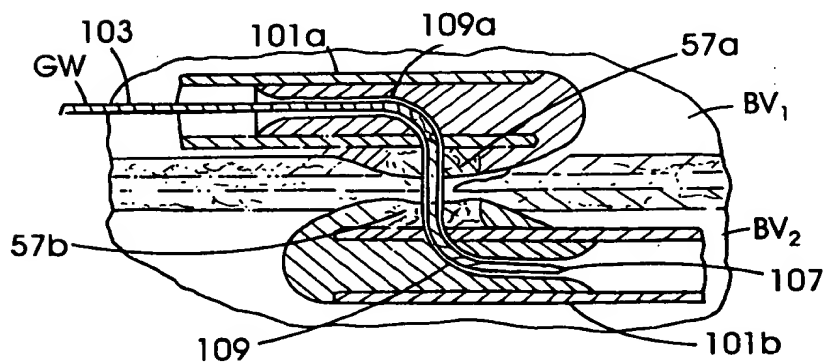
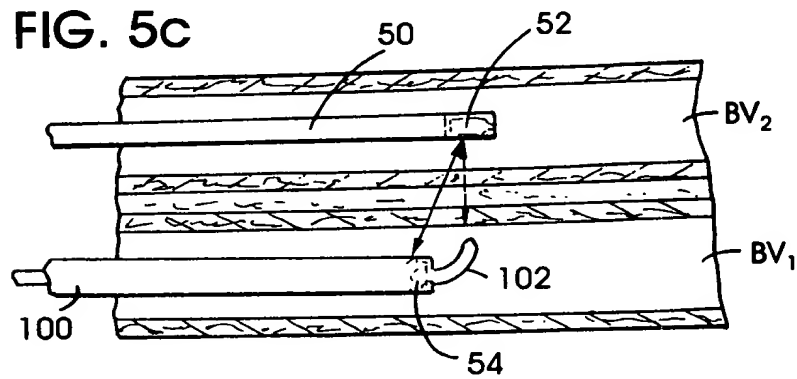


FIG. 5d

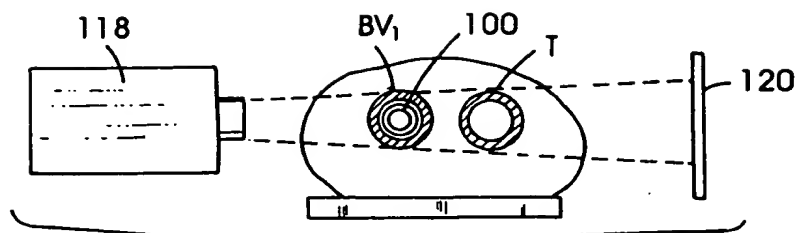


FIG. 5e

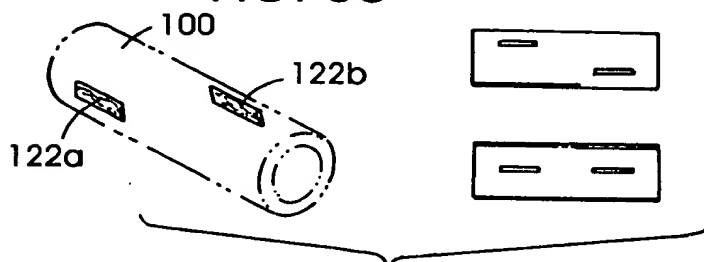


FIG. 5e'

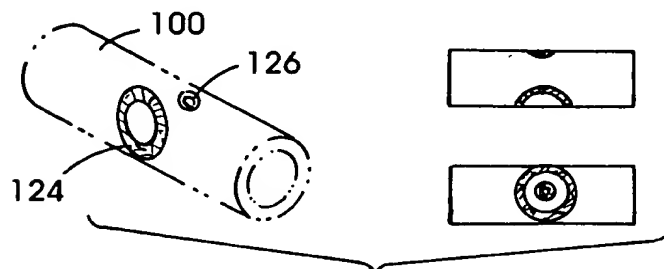


FIG. 5e''

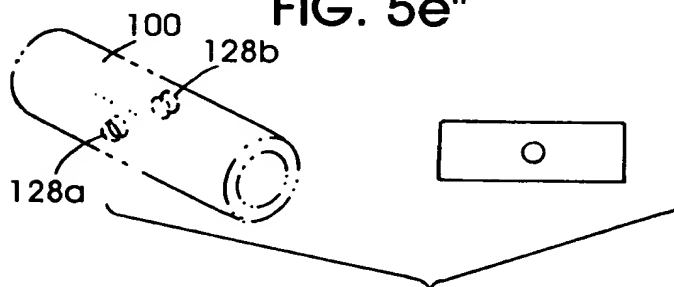


FIG. 5e'''

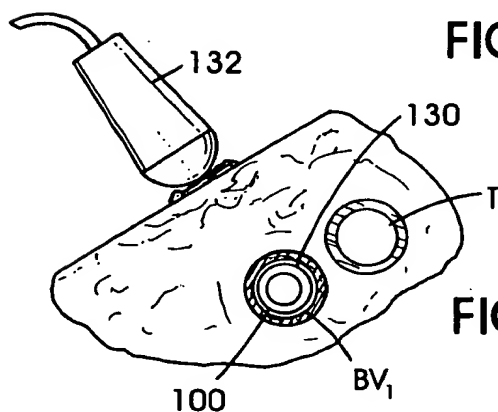


FIG. 5f

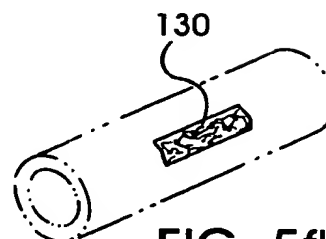


FIG. 5f'

FIG. 5g

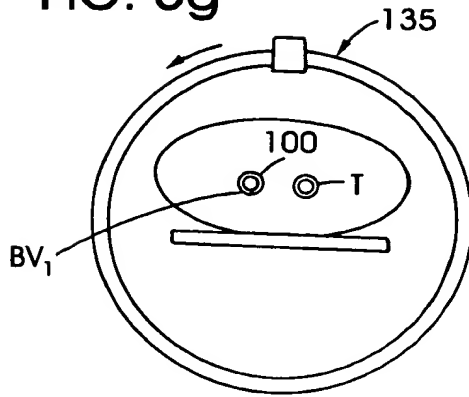


FIG. 5g'

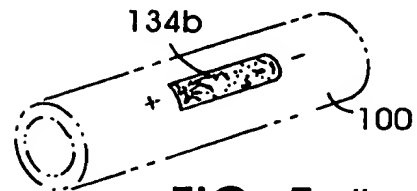
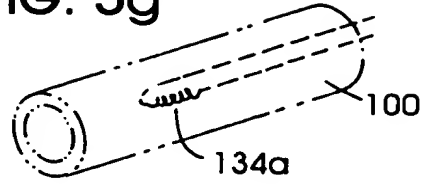


FIG. 5g''

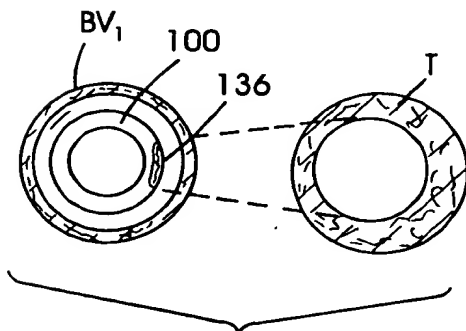


FIG. 5h

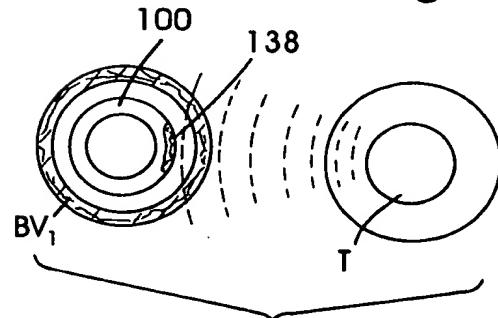


FIG. 5i

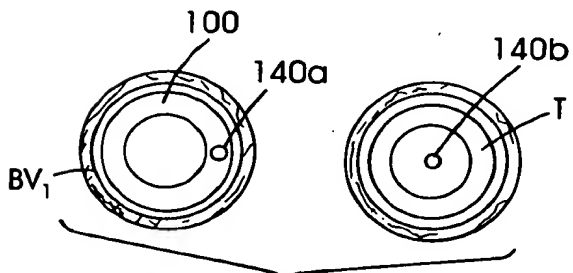


FIG. 5j

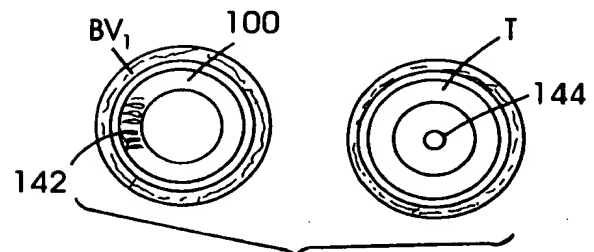


FIG. 5k

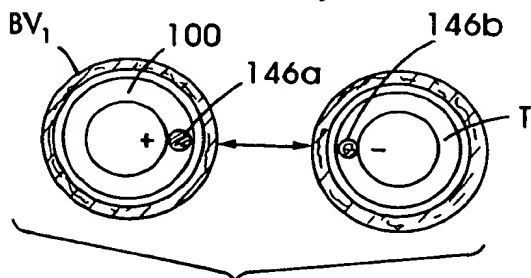


FIG. 5l

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FIG. 6a

100a

10

102

101

114a

112a

102

BV

FIG. 6d

This cross-sectional view shows the device after the second conductive layer has been formed over the first. The first conductive layer (100) is now covered by a second conductive layer (100d). A conductive paste (180) is applied at the junction where the two layers meet, forming a bridge (184) that connects them. This bridge is positioned above the substrate (BV) and the first conductive layer's end (114d). The top surface of the second conductive layer is labeled 102.

$$(A_1 + A_2 = A_3)$$

FIG. 6f

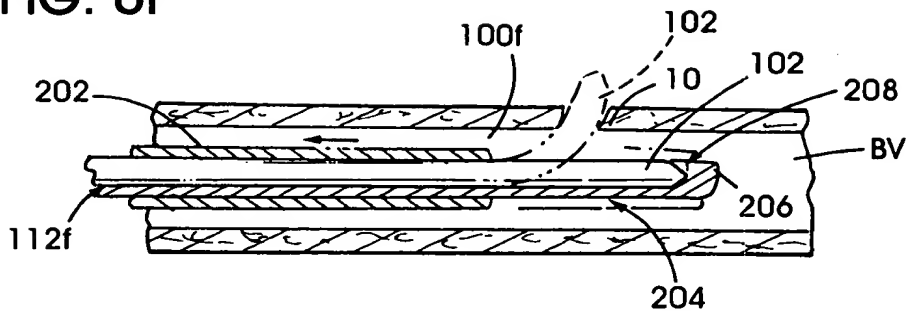


FIG. 6g

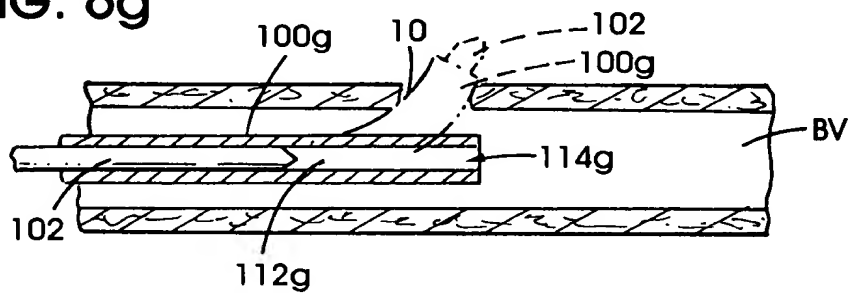


FIG. 6h

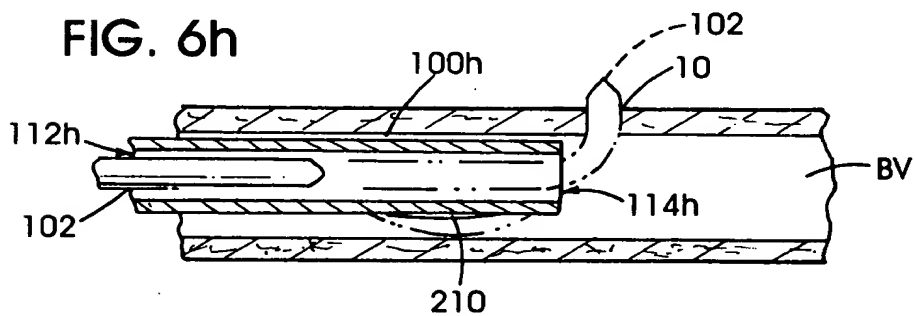
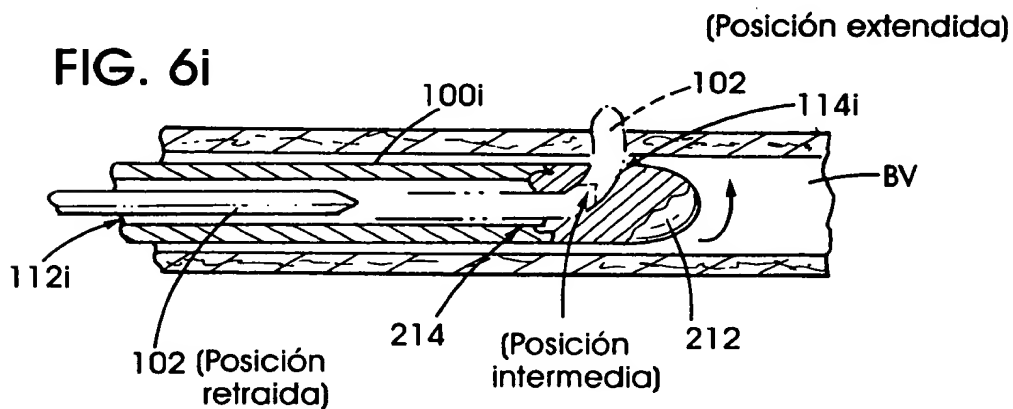
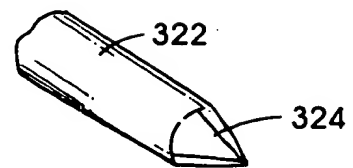
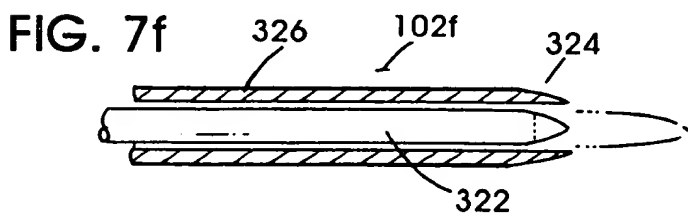
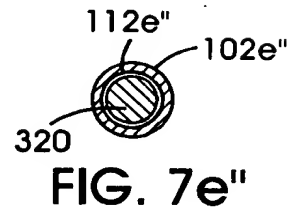
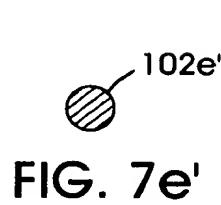
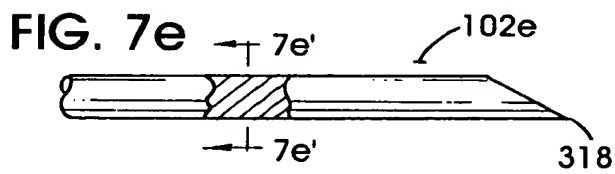
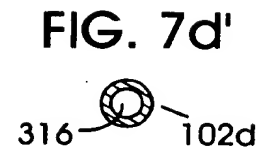
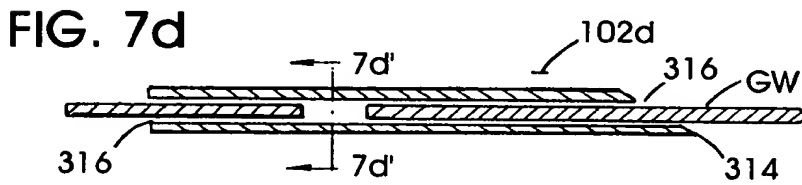
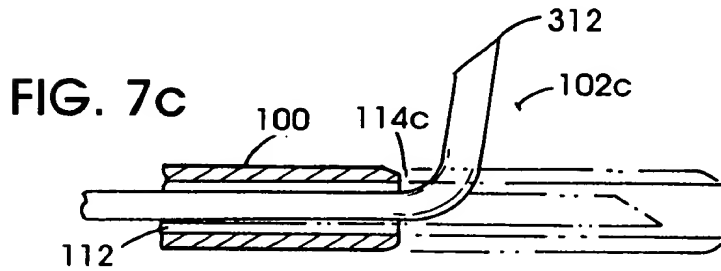
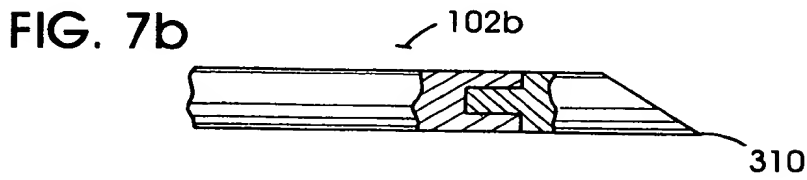
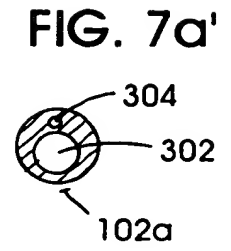
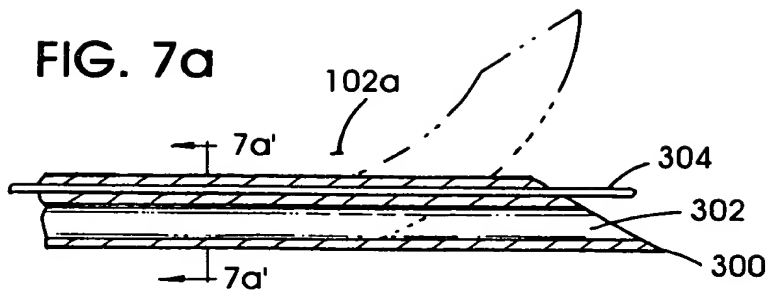
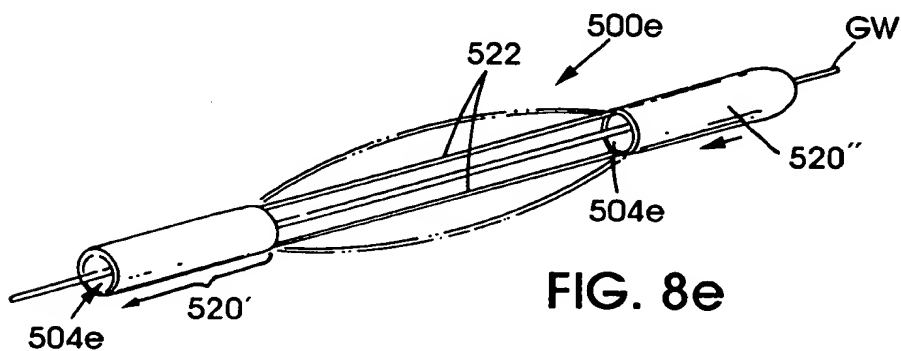
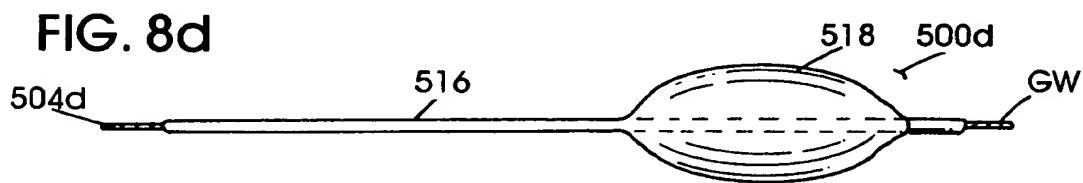
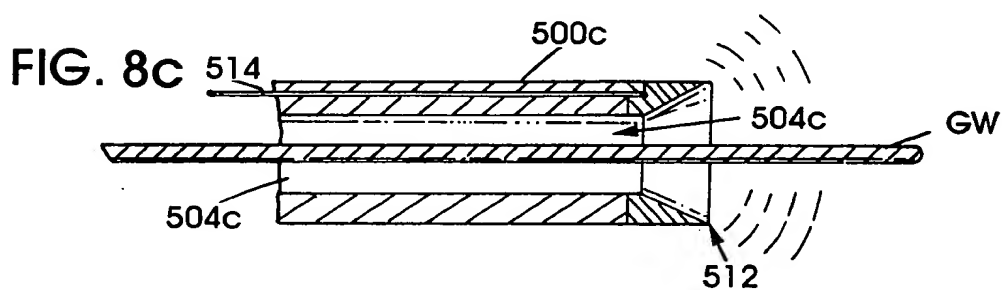
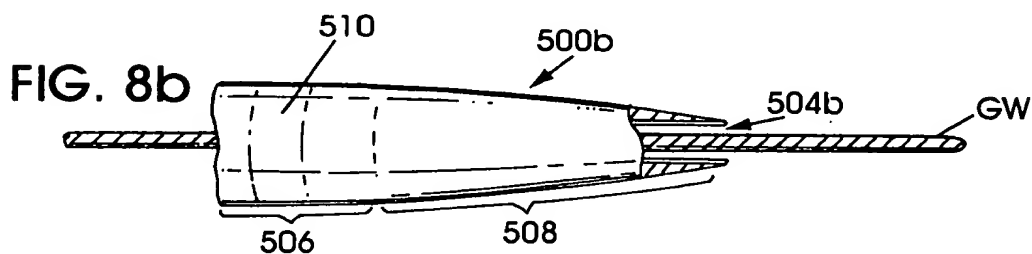
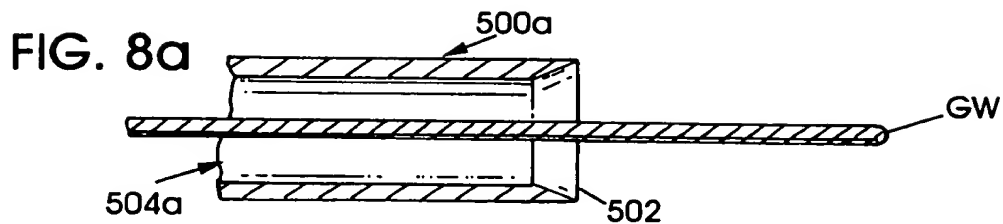


FIG. 6i



(Posición extendida)





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FIG. 8f

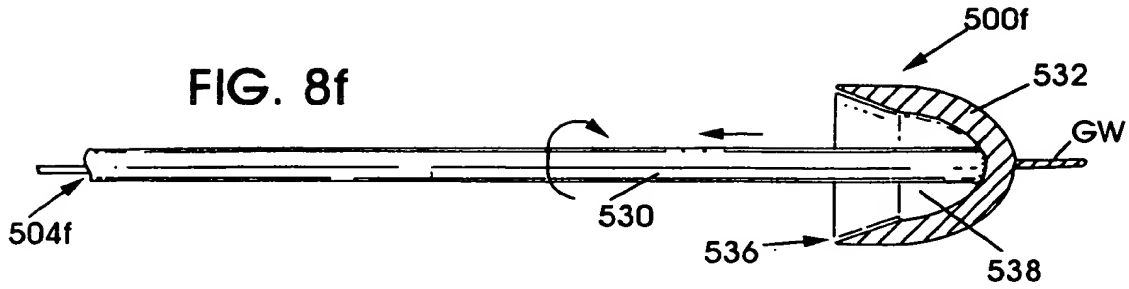


FIG. 8g

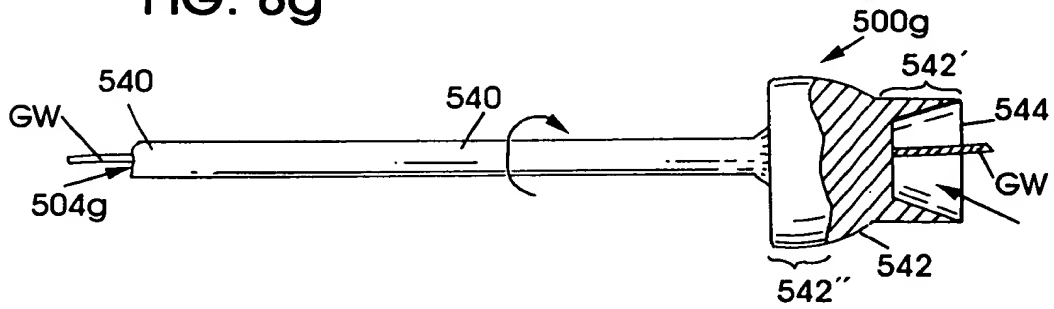


FIG. 8h

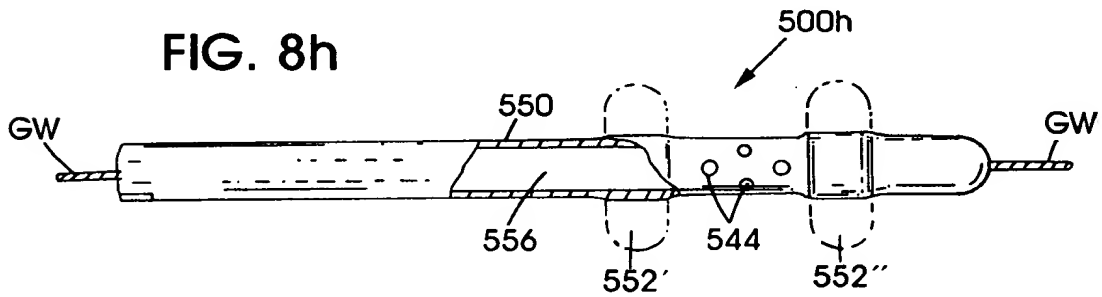


FIG. 8h''

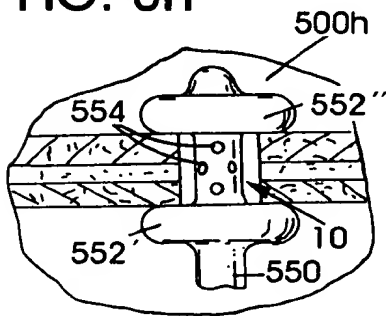


FIG. 8h'

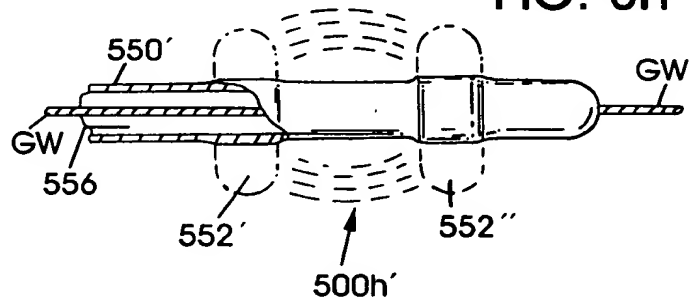


FIG. 9a

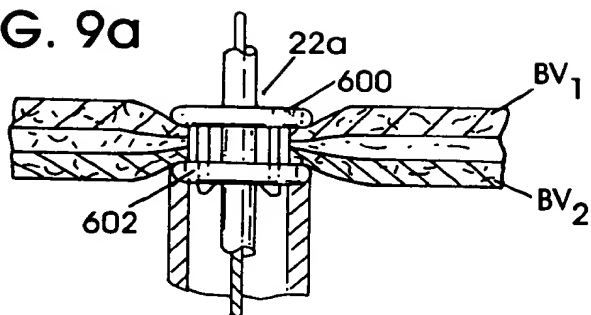


FIG. 9a'

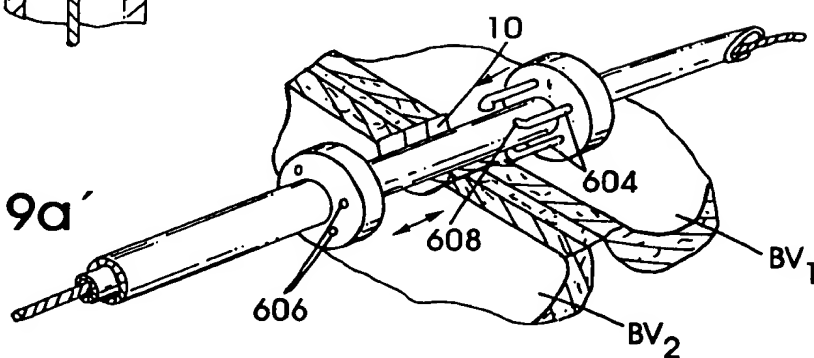


FIG. 9b

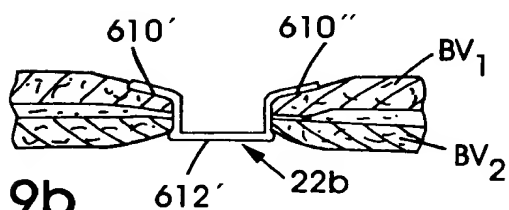


FIG. 9b''

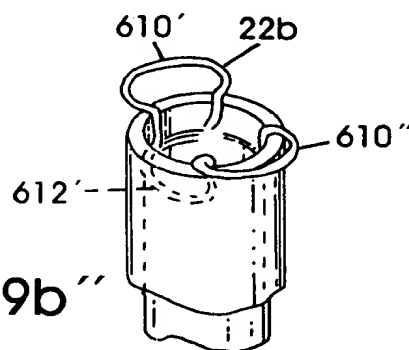


FIG. 9b'

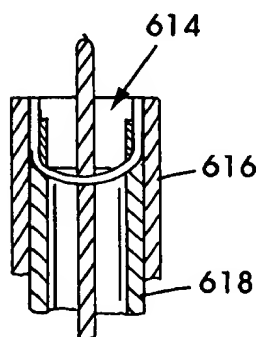
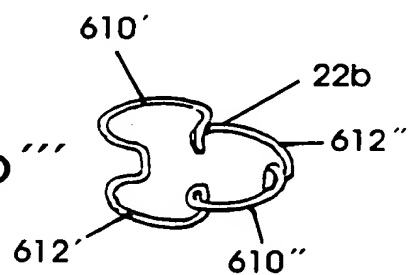


FIG. 9b'''



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FIG. 9f''''

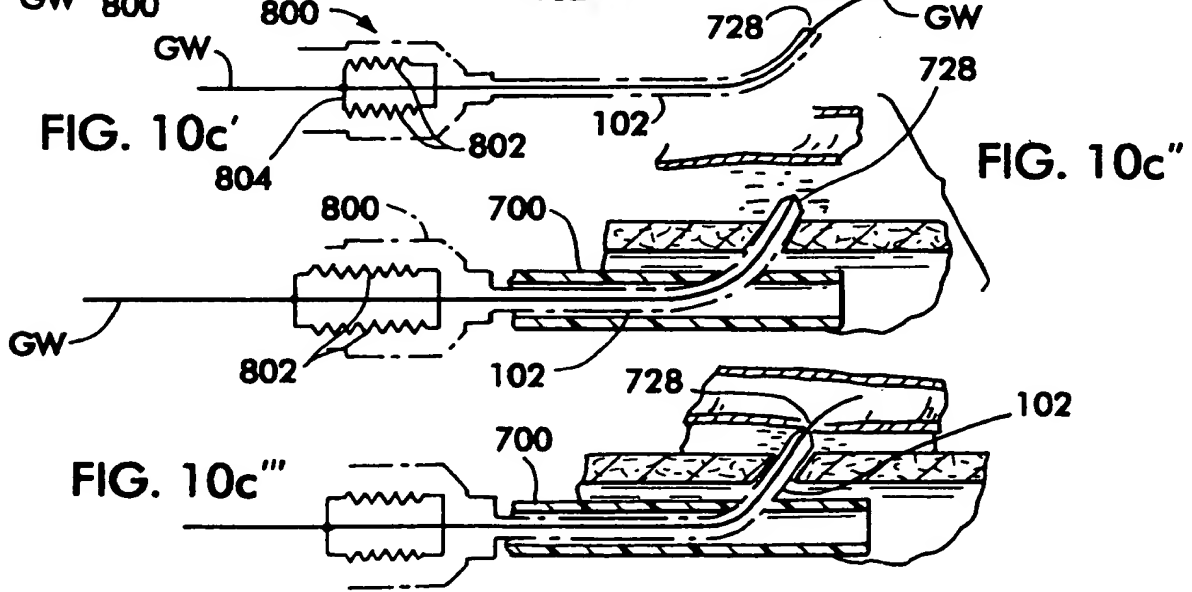
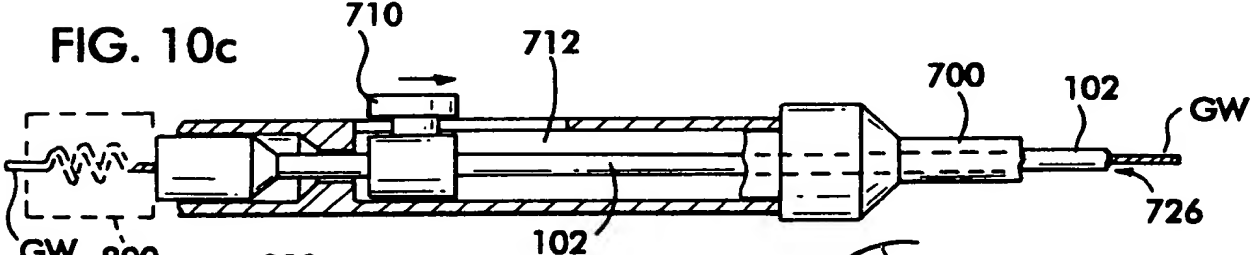
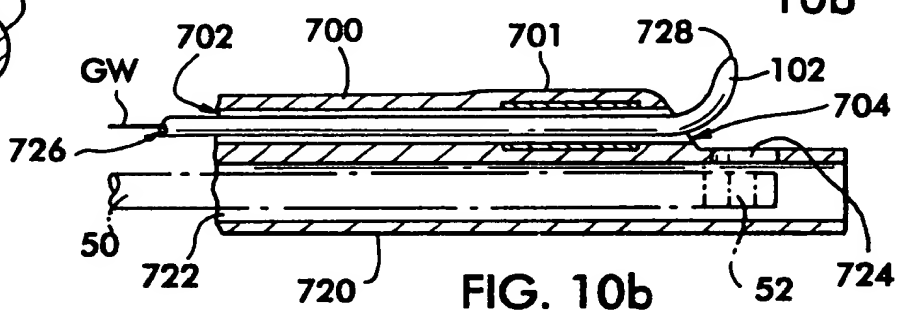
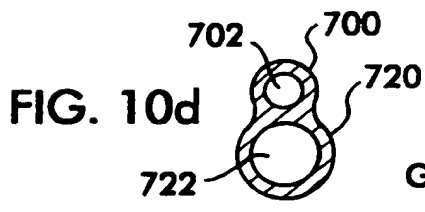
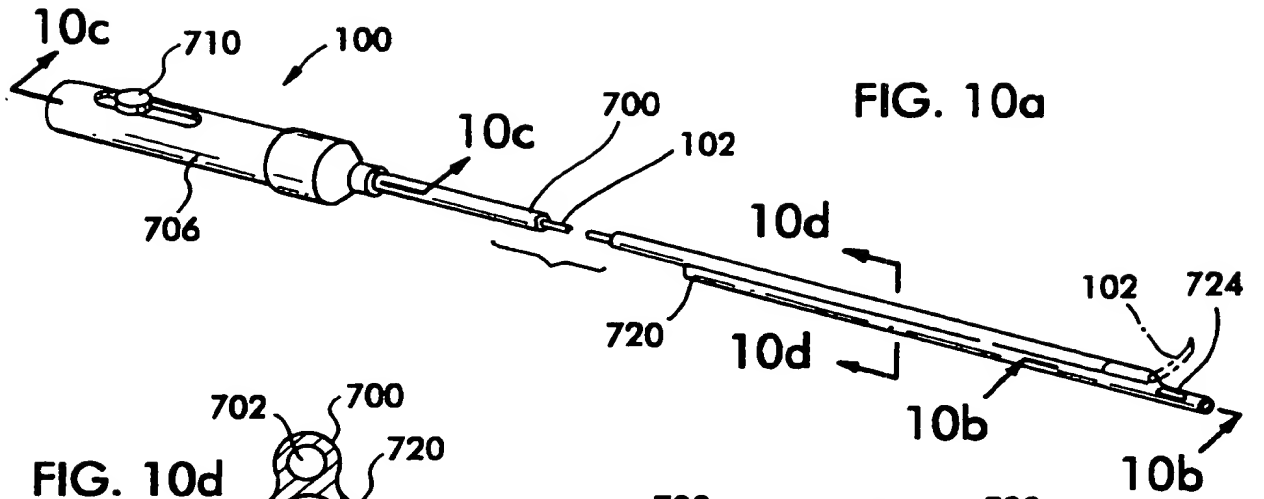


FIG. 11a

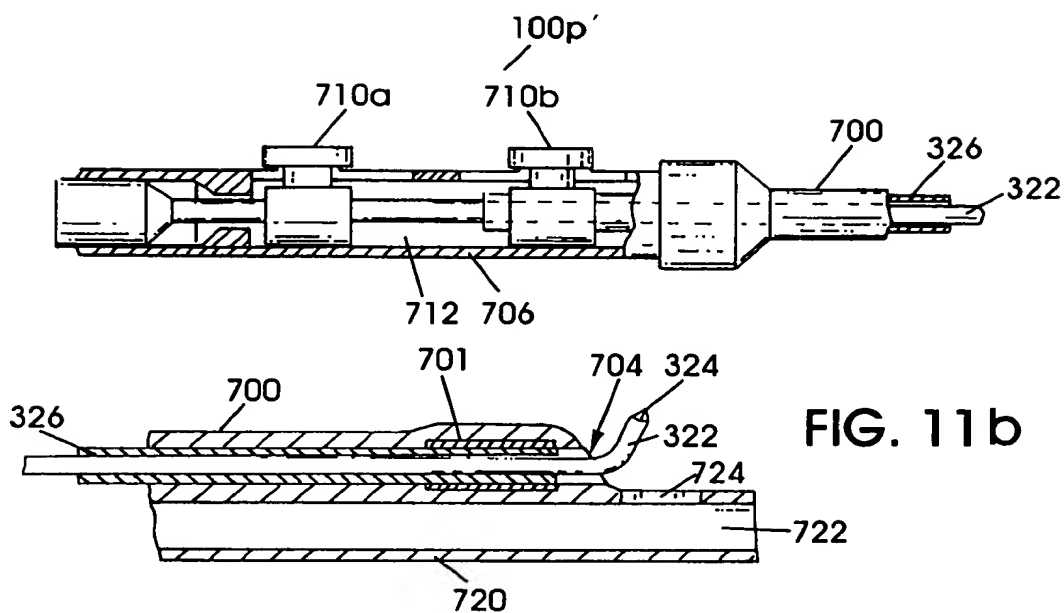


FIG. 11b

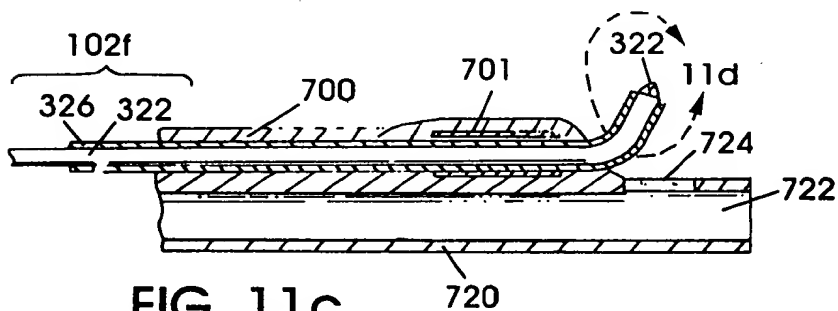


FIG. 11c

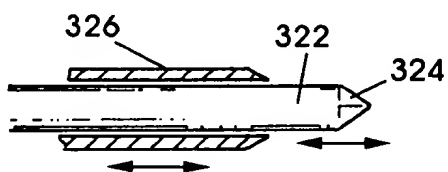


FIG. 11d

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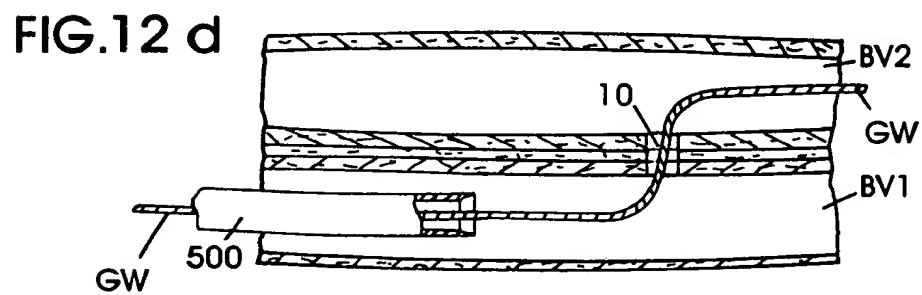
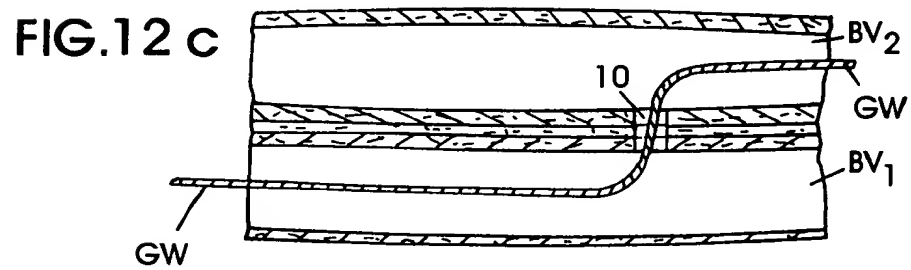
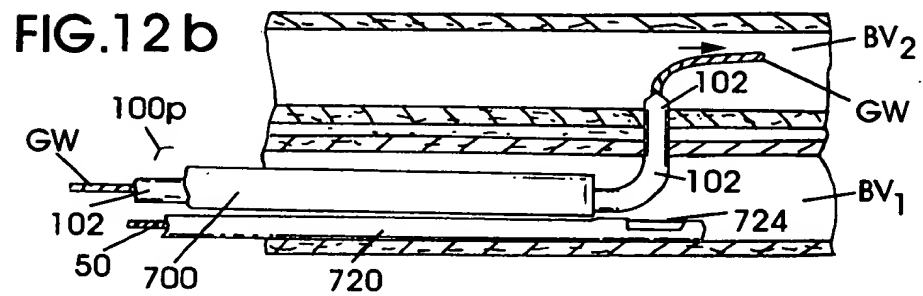
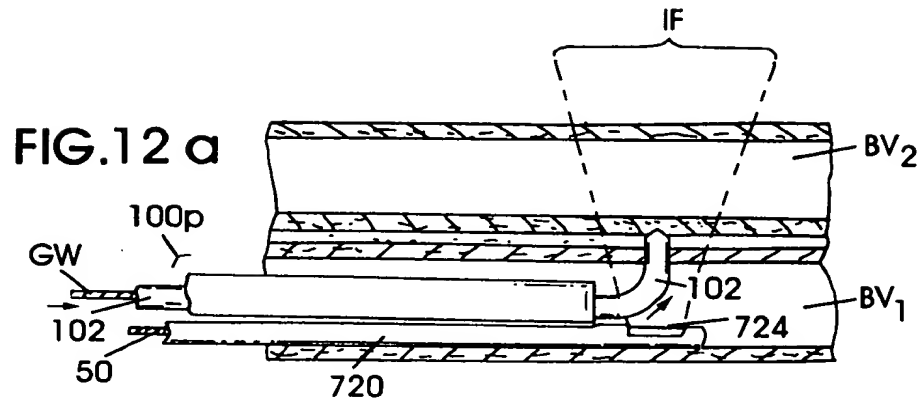


FIG. 13c

FIG. 13c is a cross-sectional view of a device. It shows a curved member 10 with a protrusion 326. The member 10 is positioned between two layers, BV1 and BV2, which are separated by a gap GW. The member 10 is supported by a base 720. A component 100p' is shown on the left, connected to the member 10. Other labels include 50, 700, and 724.

Fig. 13e

Fig. 13e is a cross-sectional view of a device. It shows a central core 10 with a winding structure. A component 500 is shown on the left, connected to the core. Labels BV1, BV2, and GW are present on the right side, indicating different layers or regions.

[illegible]